Switch-mode Power Rectifier 60 V, 20 A

MBR20L60CTG MBRF20L60CTG

Features and Benefits

- Low Power Loss/High Efficiency
- High Surge Capacity
- 20 A Total (10 A Per Diode Leg)
- Guard-Ring for Stress Protection
- These Devices are Pb-Free and are RoHS Compliant*

Applications

- Power Supply Output Rectification
- Power Management
- Instrumentation

Mechanical Characteristics:

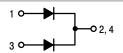
- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 50 Units Per Plastic Tube

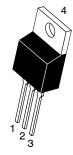


ON Semiconductor®

www.onsemi.com

SCHOTTKY BARRIER RECTIFIER 20 AMPERES 60 VOLTS



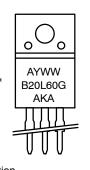


MARKING DIAGRAM

TO-220 CASE 221A STYLE 6







A = Assembly Location

Y = Year
WW = Work Week
B20L60 = Device Code
G = Pb-Free Package
AKA = Polarity Designator

ORDERING INFORMATION

Device	Package	Shipping
MBR20L60CTG	TO-220 (Pb-Free)	50 Units / Rail
MBRF20L60CTG	TO-220FP (Pb-Free)	50 Units / Rail

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS (Per Diode Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	60	V
Average Rectified Forward Current MBR20L60CT (Rated V_R) T_C = 138°C Per Diode MBRF20L60CT (Rated V_R) T_C = 123°C Per Device	I _{F(AV)}	10 20	A
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	240	А
Operating Junction Temperature (Note 1)	T _J	-55 to +150	°C
Storage Temperature	T _{stg}	- 65 to +175	°C
ESD Ratings: Machine Model = C Human Body Model = 3B		> 400 > 8000	V
Maximum Repetitive Peak Avalanche Voltage $(t_p < 1~\mu s, T_J < 150^{\circ}C, I_{AR} < 51~A)$	V_{ARM}	85	V
Maximum Single-Pulse Peak Avalanche Voltage ($t_p < 1~\mu s,~T_J < 150^{\circ}C,~I_{AR} < 51~A$)	V _{ASM}	85	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Charact	eristic	Symbol	Value	Unit
Maximum Thermal Resistance				°C/W
MBR20L60CTG	Junction-to-Case	$R_{ heta JC}$	2.3	
	Junction-to-Ambient	$R_{ hetaJA}$	70	
MBRF20L60CTG	Junction-to-Case	$R_{ hetaJC}$	5.2	
	Junction-to-Ambient	$R_{ hetaJA}$	75	

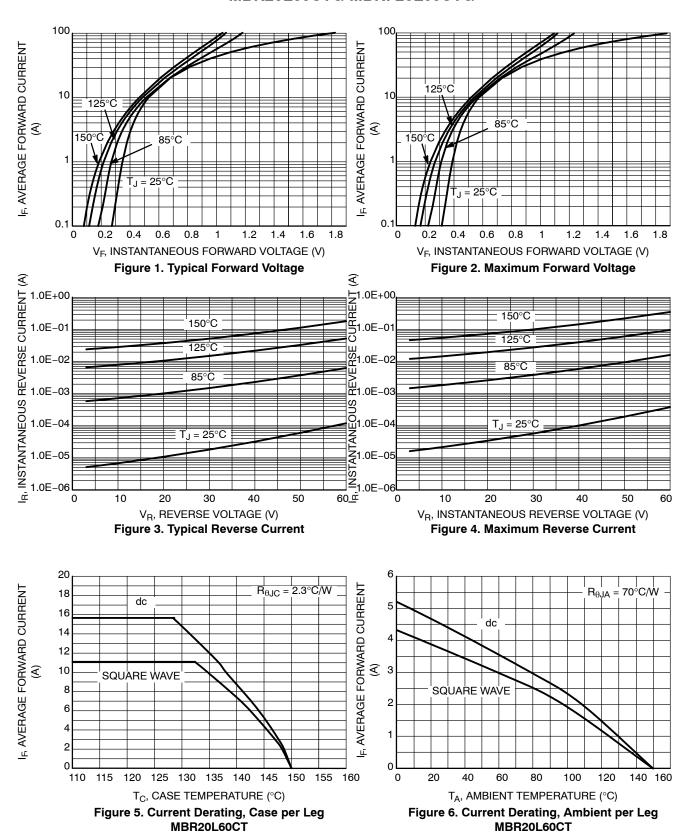
ELECTRICAL CHARACTERISTICS (Per Diode Leg)

Characteristic	Symbol	Тур	Max	Unit
Maximum Instantaneous Forward Voltage (Note 2) $(I_F = 10 \text{ A}, T_C = 25^{\circ}\text{C})$ $(I_F = 10 \text{ A}, T_C = 125^{\circ}\text{C})$	VF	0.53 0.49	0.57 0.54	V
$(I_F = 20 \text{ A}, T_C = 25^{\circ}\text{C})$ $(I_F = 20 \text{ A}, T_C = 125^{\circ}\text{C})$		0.68 0.64	0.73 0.69	
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, $T_C = 25^{\circ}C$) (Rated DC Voltage, $T_C = 125^{\circ}C$)	İR	118 52	380 96	μA mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width = 300 µs, Duty Cycle ≤ 2.0%.

^{1.} The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.



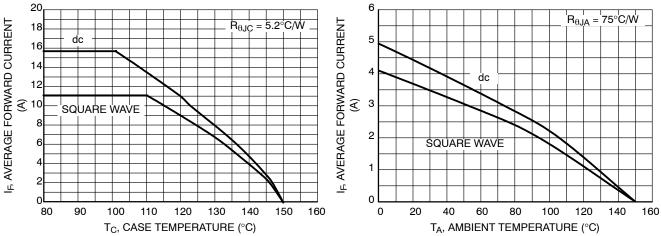


Figure 7. Current Derating, Case per Leg MBRF20L60CT

Figure 8. Current Derating, Ambient per Leg MBRF20L60CT

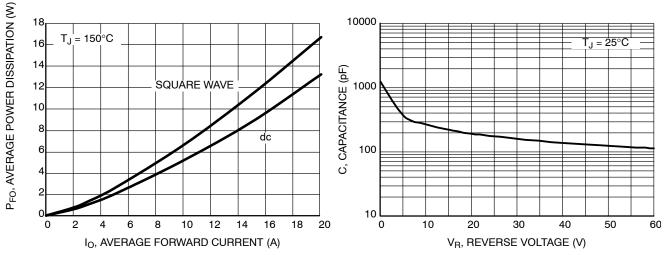


Figure 9. Forward Power Dissipation

Figure 10. Capacitance

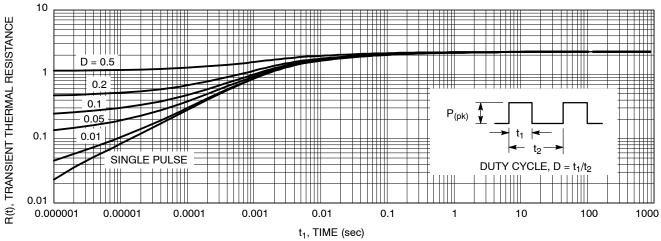


Figure 11. Thermal Response Junction-to-Case, per Leg for MBR20L60CT

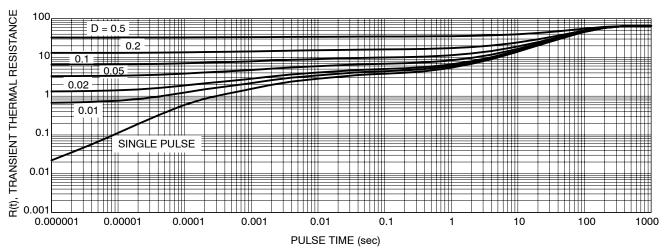


Figure 12. Thermal Response Junction-to-Ambient, per Leg for MBR20L60CT

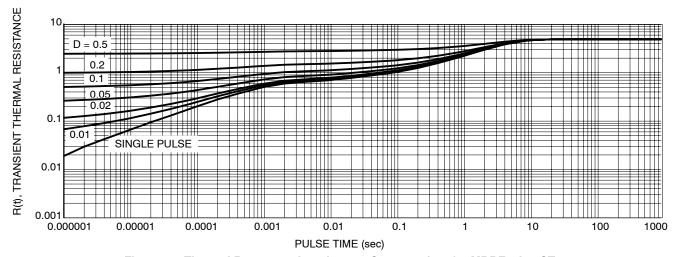


Figure 13. Thermal Response Junction-to-Case, per Leg for MBRF20L60CT

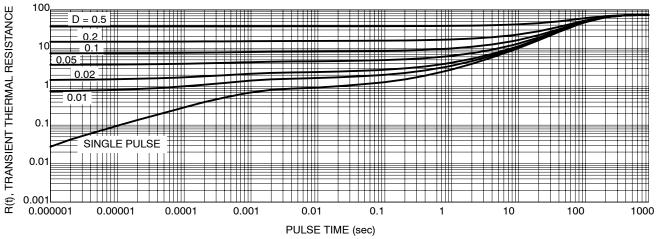


Figure 14. Thermal Response Junction-to-Ambient, per Leg for MBRF20L60CT

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MECHANICAL CASE OUTLINE





SCALE 1:1

TO-220 FULLPAK CASE 221D-03 ISSUE K

DATE 27 FEB 2009



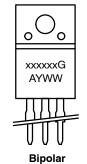
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH
- 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.

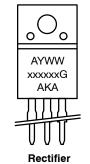
	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.617	0.635	15.67	16.12
В	0.392	0.419	9.96	10.63
C	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100 BSC		2.54 BSC	
Н	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
N	0.200 BSC		5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

-T- SEATING PLANE -B--Y-– **D** з PL | ⊕ | 0.25 (0.010) M | B M | Y

MARKING DIAGRAMS







= Assembly Location xxxxxx = Specific Device Code G = Pb-Free Package Υ = Year Α = Assembly Location WW = Work Week Υ = Year XXXXXX = Device Code = Work Week = Pb-Free Package WW G AKA = Polarity Designator

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DESCRIPTION:	TO-220 FULLPAK		PAGE 1 OF 1	

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